

SEMIPACK® 3

Rectifier Diode Modules

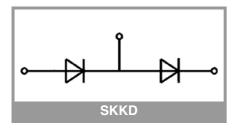
SKKD 353/16

Features*

- Industrial standard package
- Electrically insulated base plate
- Heat transfer through aluminum oxide ceramic insulated metal base plate
- Chip soldered on direct copper bonded Al₂O₃ ceramic
- UL recognition, file no. E63532

Absolute Maximum Ratings								
Symbol	Conditions		Values	Unit				
Recitifier	Diode			•				
I _{FAV}	sin. 180°	T _c = 85 °C	350	Α				
	T _{j max} = 130 °C	T _c = 100 °C	260	Α				
I _{FRMS}	continuous operation		580	Α				
I _{FSM}	10 ms	T _j = 25 °C	10500	Α				
		T _j = 130 °C	9500	Α				
i ² t	10 ms	T _j = 25 °C	551250	A ² s				
		T _j = 130 °C 451250		A ² s				
V_{RSM}	T _j = 25 °C		1700	V				
V_{RRM}	T _j = 25 °C		1600	V				
Tj			-40 130					
Module	•			•				
T _{stg}			-40 125	°C				
V _{isol}	0 0 1 EO Hay r m 0	1 min	3000	V				
i	a.c.; 50 Hz; r.m.s.	1 s	3600	V				

Characteristics									
Symbol	Conditions	min.	typ.	max.	Unit				
Diode	•		•						
V_{F}	$T_j = 25 ^{\circ}\text{C}, I_F = 750 \text{A}$				1.38	V			
V_{F0}	T _j = 130 °C				0.84	V			
r _F	T _j = 130 °C				0.67	mΩ			
I _R	$T_j = 130$ °C, $V_{RD} = V_{RRM}$				15	mA			
R _{th(j-c)}		per chip			0.09	K/W			
	cont.	per module			0.045	K/W			
R _{th(j-c)}	sin. 180°	per chip			0.092	K/W			
		per module			0.046	K/W			
Module									
R _{th(c-s)}	chip			0.08		K/W			
	module			0.04		K/W			
Ms	to heatsink M5		4.25		5.75	Nm			
Mt	to terminals M8		7.65		10.35	Nm			
а					5 * 9.81	m/s²			
w				410		g			



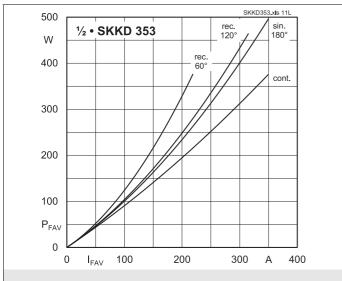


Fig. 11L: Power dissipation per diode vs. forward current

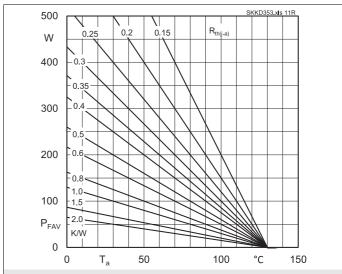


Fig. 11R: Power dissipation per diode vs. ambient temperature

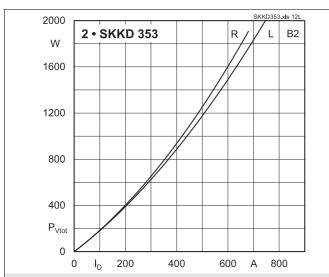


Fig. 12L: Power dissipation of two modules vs. direct current

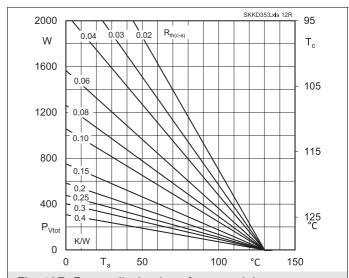


Fig. 12R: Power dissipation of two modules vs. case temperature

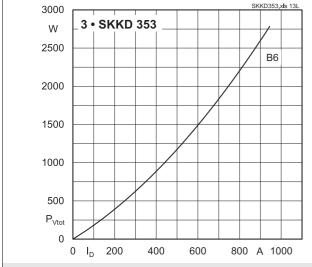


Fig. 13L: Power dissipation of three modules vs. direct current

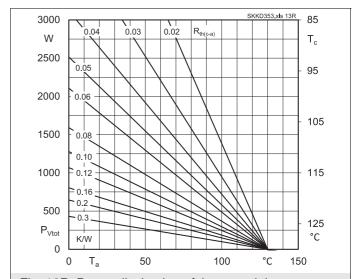


Fig. 13R: Power dissipation of three modules vs. case temperature

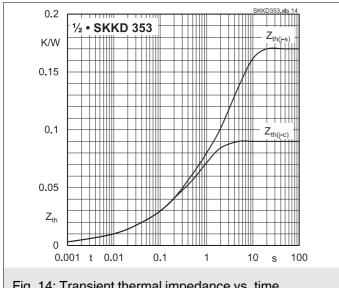


Fig. 14: Transient thermal impedance vs. time

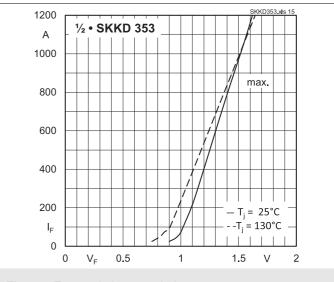
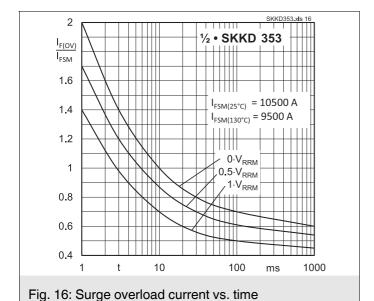
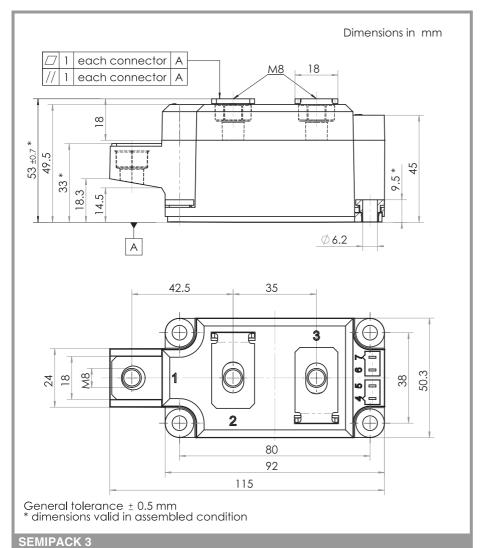
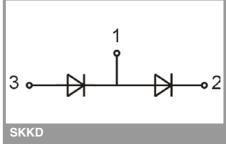


Fig. 15: Forward characteristics



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

*IMPORTANT INFORMATION AND WARNINGS

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